

# EMB1S THRU EMB6S

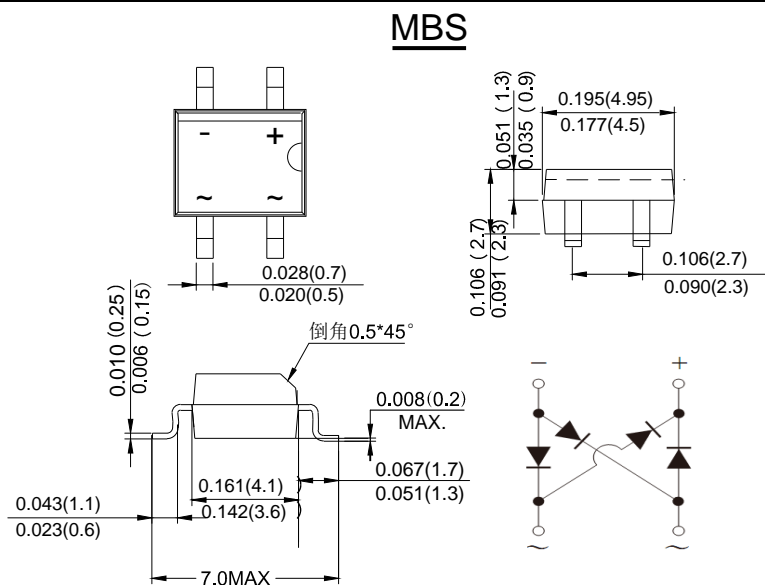
SINGLE PHASE 0.8AMP SUPER FAST GLASS PASSIVATED BRIDGE RECTIFIER

## Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

## Mechanical Data

- Case:Reliable low cost construction utilizing molded plastic technique
- Terminals:Plated Leads Solderable per MIL-STD-202,Method208
- Polarity:As Marked on Case
- Mounting Position:Any
- Marking:Type Number



dimensions in inches and (millimeters)

## Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

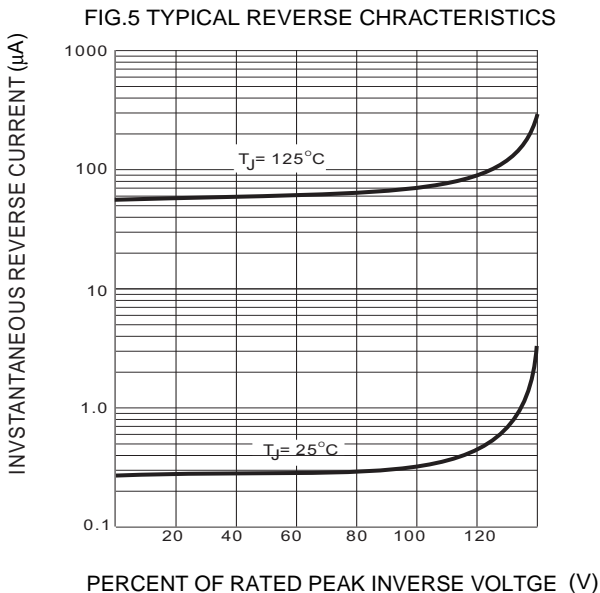
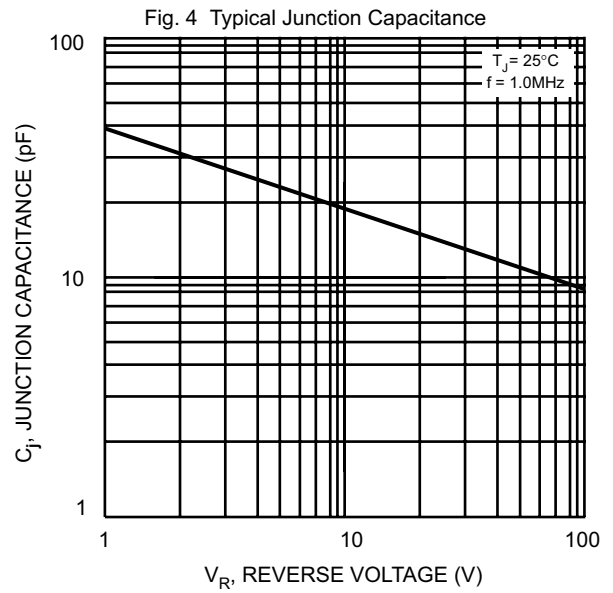
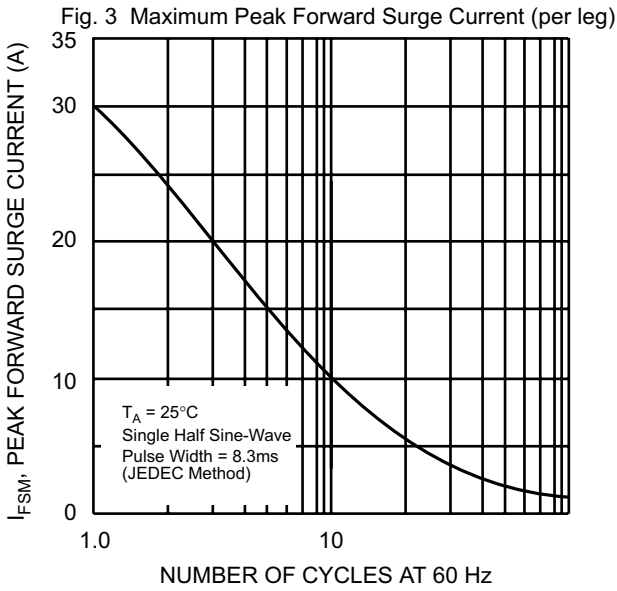
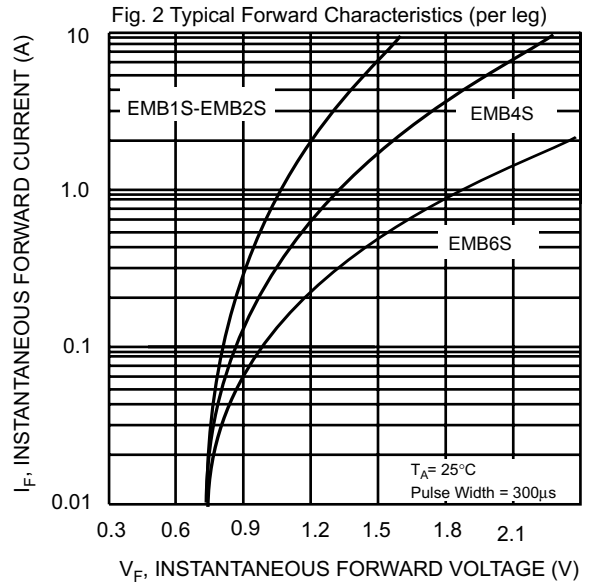
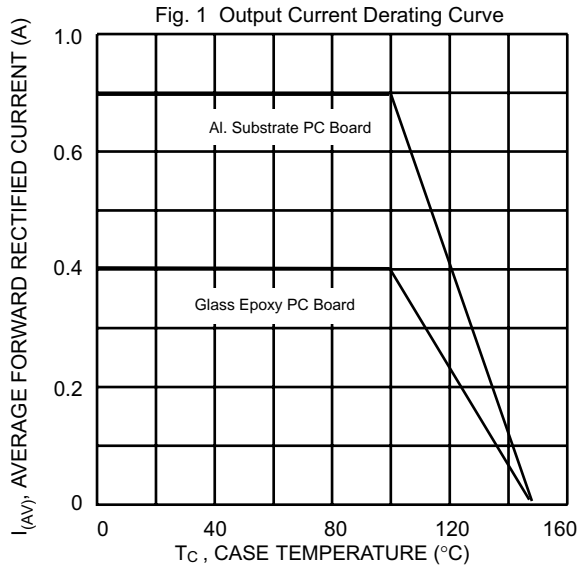
TYPE NUMBER	SYMBOL	EMB1S	EMB2S	EMB4S	EMB6S	UNITS
Peak Repetitive Reverse Voltage	$V_{RRM}$	100	200	400	600	V
Working Peak Reverse Voltage	$V_{RWM}$					
DC Blocking Voltage	$V_{DC}$					
RMS Reverse Voltage	$V_{RMS}$	70	140	280	420	V
Average Rectified Output Current (Note 1)@ $T_c=100^\circ C$ (Note 2)@ $T_c=100^\circ C$	$I_F(AV)$	0.5 0.8				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30				A
$I^2t$ Rating for Fusing ( $t < 8.3ms$ )	$I^2t$	3.735				$A^2s$
Forward Voltage per element @ $I_F=0.8A$	$V_{FM}$	0.95		1.25	1.75	V
Peak Reverse Current @ $T_A=25^\circ C$ At Rated DC Blocking Voltage @ $T_A=125^\circ C$	$I_R$	5.0 200				$\mu A$
Maximum reverse recovery time (Note 3)	$T_{RR}$	35				ns
Typical Junction Capacitance per leg (Note 4)	$C_J$	13				pF
Typical Thermal Resistance per leg	$R_{\theta JA}$	60				$^\circ C/W$
	$R_{\theta JL}$	16				
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55to+150				$^\circ C$

Note:1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.

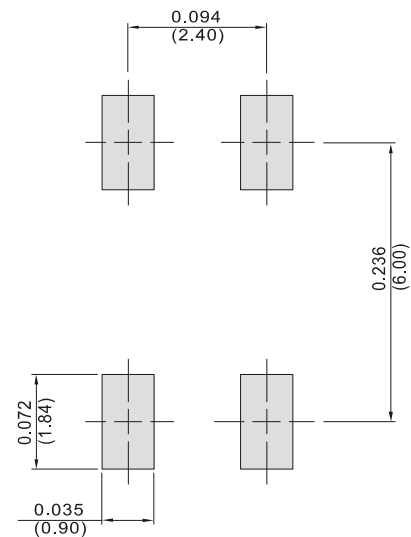
2. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.

3. Reverse Recovery Test Conditions:  $I_F=0.5A$ ,  $I_R=1A$ ,  $I_{rr}=0.25A$ .

4. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.



**FIG.6 MOUNTING PAD LAYOUT**



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